Silicon Labs - EFM32LG880F256-QFP100 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	EBI/EMI, I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32lg880f256-qfp100

3.1.23 Analog Comparator (ACMP)

The Analog Comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. Inputs can either be one of the selectable internal references or from external pins. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.24 Voltage Comparator (VCMP)

The Voltage Supply Comparator is used to monitor the supply voltage from software. An interrupt can be generated when the supply falls below or rises above a programmable threshold. Response time and thereby also the current consumption can be configured by altering the current supply to the comparator.

3.1.25 Analog to Digital Converter (ADC)

The ADC is a Successive Approximation Register (SAR) architecture, with a resolution of up to 12 bits at up to one million samples per second. The integrated input mux can select inputs from 8 external pins and 6 internal signals.

3.1.26 Digital to Analog Converter (DAC)

The Digital to Analog Converter (DAC) can convert a digital value to an analog output voltage. The DAC is fully differential rail-to-rail, with 12-bit resolution. It has two single ended output buffers which can be combined into one differential output. The DAC may be used for a number of different applications such as sensor interfaces or sound output.

3.1.27 Operational Amplifier (OPAMP)

The EFM32LG features up to 3 Operational Amplifiers. The Operational Amplifier is a versatile general purpose amplifier with rail-to-rail differential input and rail-to-rail single ended output. The input can be set to pin, DAC or OPAMP, whereas the output can be pin, OPAMP or ADC. The current is programmable and the OPAMP has various internal configurations such as unity gain, programmable gain using internal resistors etc.

3.1.28 Low Energy Sensor Interface (LESENSE)

The Low Energy Sensor Interface (LESENSE^{TM}), is a highly configurable sensor interface with support for up to 16 individually configurable sensors. By controlling the analog comparators and DAC, LESENSE is capable of supporting a wide range of sensors and measurement schemes, and can for instance measure LC sensors, resistive sensors and capacitive sensors. LESENSE also includes a programmable FSM which enables simple processing of measurement results without CPU intervention. LESENSE is available in energy mode EM2, in addition to EM0 and EM1, making it ideal for sensor monitoring in applications with a strict energy budget.

3.1.29 Backup Power Domain

The backup power domain is a separate power domain containing a Backup Real Time Counter, BURTC, and a set of retention registers, available in all energy modes. This power domain can be configured to automatically change power source to a backup battery when the main power drains out. The backup power domain enables the EFM32LG to keep track of time and retain data, even if the main power source should drain out.

3.1.30 Advanced Encryption Standard Accelerator (AES)

The AES accelerator performs AES encryption and decryption with 128-bit or 256-bit keys. Encrypting or decrypting one 128-bit data block takes 52 HFCORECLK cycles with 128-bit keys and 75 HFCORECLK cycles with 256-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

3.1.31 General Purpose Input/Output (GPIO)

In the EFM32LG, there are up to 93 General Purpose Input/Output (GPIO) pins, which are divided into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

Module	Configuration	Pin Connections
OPAMP	Full configuration	Outputs: OPAMP_OUTx, OPAMP_OUTxALT, Inputs: OPAMP_Px, OPAMP_Nx
AES	Full configuration	NA
GPIO	52 pins	Available pins are shown in 5.18.3 GPIO Pinout Overview
LCD	Full configuration	LCD_SEG[17:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
EM1 current (Production test condition = 14 MHz)	I_{EM1}	48 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	63	75	µA/MHz
		48 MHz HFXO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	65	76	µA/MHz
		28 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	64	75	µA/MHz
		28 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	65	77	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	65	76	µA/MHz
		21 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	66	78	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	67	79	µA/MHz
		14 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	68	82	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	68	81	µA/MHz
		11 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	70	83	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	74	87	µA/MHz
		6.6 MHz HFRCO, all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	76	89	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=25°C	—	106	120	µA/MHz
		1.2 MHz HFRCO. all peripheral clocks disabled, V_{DD}= 3.0 V, T_{AMB}=85°C	—	112	129	µA/MHz
EM2 current	I_{EM2}	EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.95[1]	1.7[1]	µA
		EM2 current with RTC prescaled to 1 Hz, 32.768 kHz LFRCO, V_{DD}= 3.0 V, T_{AMB}=85°C	—	3.0[1]	4.0[1]	µA
EM3 current	I_{EM3}	V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.65	1.3	µA
		V_{DD}= 3.0 V, T_{AMB}=85°C	—	2.65	4.0	µA
EM4 current	I_{EM4}	V_{DD}= 3.0 V, T_{AMB}=25°C	—	0.020	0.055	µA
		V_{DD}= 3.0 V, T_{AMB}=85°C	—	0.44	0.90	µA

Note:

1. Using backup RTC.

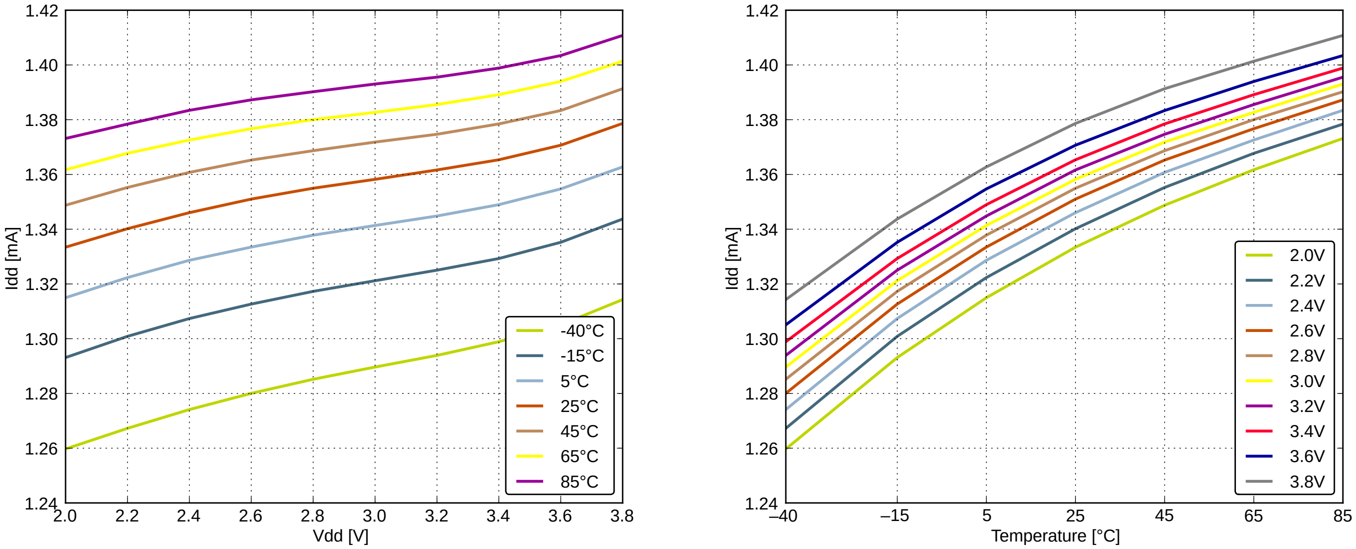

Figure 4.3. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 21 MHz

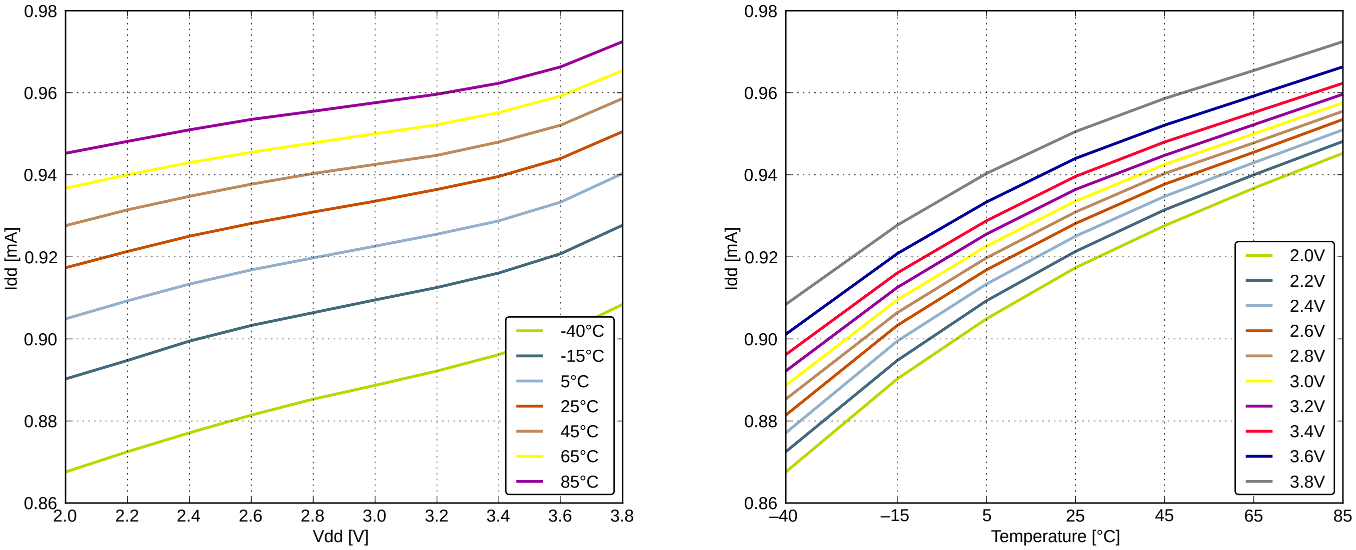

Figure 4.4. EM1 Current Consumption with all Peripheral Clocks Disabled and HFRCO Running at 14 MHz

5.3 EFM32LG280 (LQFP100)

5.3.1 Pinout

The EFM32LG280 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

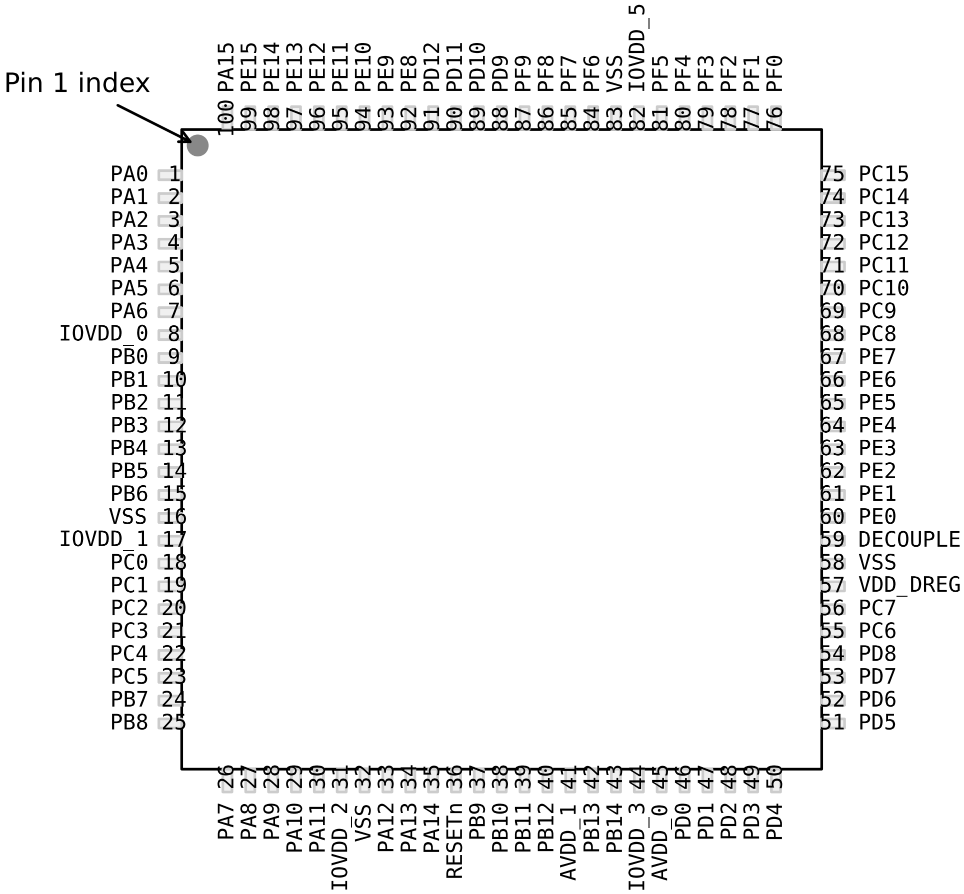

Figure 5.5. EFM32LG280 Pinout (top view, not to scale)

Table 5.7. Device Pinout

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
1	PA0		EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1		EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD07	PE15	PE15	PE15					External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15	PA15	PA15					External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0	PA0	PA0					External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3	PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
US2_TX	PC2	PB3						USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

5.4.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32LG290 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.12. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	PA11	PA10	PA9	PA8	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	PB15	PB14	PB13	PB12	PB11	PB10	PB9	PB8	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	PD15	PD14	PD13	PD12	PD11	PD10	PD9	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0
Port F	—	—	—	—	—	—	PF9	PF8	PF7	PF6	PF5	PF4	PF3	PF2	PF1	PF0

5.4.4 Opamp Pinout Overview

The specific opamp terminals available in EFM32LG290 is shown in the following figure.

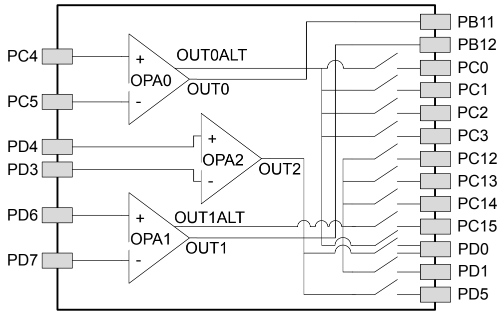

Figure 5.8. Opamp Pinout

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
A3	PE12		EBI_AD04 #0/1/2	TIM1_CC2 #1	US0_RX #3 US0_CLK #0 I2C0_SDA #6	CMU_CLK1 #2 LES_ALTEX6 #0
A4	PE9		EBI_AD01 #0/1/2	PCNT2_S1IN #1		
A5	PD11		EBI_CS2 #0/1/2			
A6	PD9		EBI_CS0 #0/1/2			
A7	PF7		EBI_BL1 #0/1/2	TIM0_CC1 #2	U0_RX #0	
A8	PF5		EBI_REn #0/2	TIM0_CDTI2 #2/5		PRS_CH2 #1
A9	PF4		EBI_WEn #0/2	TIM0_CDTI1 #2/5		PRS_CH1 #1
A10	PF2		EBI_ARDY #0/1/2	TIM0_CC2 #5	LEU0_TX #4	ACMP1_O #0 DBG_SWO #0 GPIO_EM4WU4
A11	USB_VREGI					
A12	USB_VREGO					
A13	PF11				U1_RX #1	
B1	PA15		EBI_AD08 #0/1/2	TIM3_CC2 #0		
B2	PE13		EBI_AD05 #0/1/2		US0_TX #3 US0_CS #0 I2C0_SCL #6	LES_ALTEX7 #0 ACMP0_O #0 GPIO_EM4WU5
B3	PE11		EBI_AD03 #0/1/2	TIM1_CC1 #1	US0_RX #0	LES_ALTEX5 #0 BOOT_RX
B4	PE8		EBI_AD00 #0/1/2	PCNT2_S0IN #1		PRS_CH3 #1
B5	PD12		EBI_CS3 #0/1/2			
B6	PD10		EBI_CS1 #0/1/2			
B7	PF8		EBI_WEn #1	TIM0_CC2 #2		ETM_TCLK #1
B8	PF6		EBI_BL0 #0/1/2	TIM0_CC0 #2	U0_TX #0	
B9	PF3		EBI_ALE #0	TIM0_CDTI0 #2/5		PRS_CH0 #1 ETM_TD3 #1
B10	PF1			TIM0_CC1 #5 LETIM0_OUT1 #2	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0/1/2/3 GPIO_EM4WU3
B11	PF12					
B12	USB_VBUS	USB 5.0 V VBUS input.				
B13	PF10				U1_TX #1	
C1	PA1		EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
C2	PA0		EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
C3	PE10		EBI_AD02 #0/1/2	TIM1_CC0 #1	US0_TX #0	BOOT_TX
C4	PD13					ETM_TD1 #1

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
F11	PE7		EBI_A14 #0/1/2		US0_TX #1	
F12	PC8	ACMP1_CH0	EBI_A15 #0/1/2	TIM2_CC0 #2	US0_CS #2	LES_CH8 #0
F13	PC9	ACMP1_CH1	EBI_A09 #1/2	TIM2_CC1 #2	US0_CLK #2	LES_CH9 #0 GPIO_EM4WU2
G1	PB3		EBI_A19 #0/1/2	PCNT1_S0IN #1	US2_TX #1	
G2	PB4		EBI_A20 #0/1/2	PCNT1_S1IN #1	US2_RX #1	
G3	IOVDD_2	Digital IO power supply 2.				
G11	PE0		EBI_A07 #0/1/2	TIM3_CC0 #1 PCNT0_S0IN #1	U0_TX #1 I2C1_SDA #2	
G12	PE1		EBI_A08 #0/1/2	TIM3_CC1 #1 PCNT0_S1IN #1	U0_RX #1 I2C1_SCL #2	
G13	PE3	BU_STAT	EBI_A10 #0		U1_RX #3	ACMP1_O #1
H1	PB5		EBI_A21 #0/1/2		US2_CLK #1	
H2	PB6		EBI_A22 #0/1/2		US2_CS #1	
H3	VSS	Ground.				
H11	VDD_DREG	Power supply for on-chip voltage regulator.				
H12	PE2	BU_VOUT	EBI_A09 #0	TIM3_CC2 #1	U1_TX #3	ACMP0_O #1
H13	PC7	ACMP0_CH7	EBI_A06 #0/1/2		LEU1_RX #0 I2C0_SCL #2	LES_CH7 #0 ETM_TD0 #2
J1	PD14				I2C0_SDA #3	
J2	PD15				I2C0_SCL #3	
J3	VSS	Ground.				
J11	IOVDD_3	Digital IO power supply 3.				
J12	PC6	ACMP0_CH6	EBI_A05 #0/1/2		LEU1_TX #0 I2C0_SDA #2	LES_CH6 #0 ETM_TCLK #2
J13	DECOUPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOUPLE}$ is required at this pin.				
K1	PC0	ACMP0_CH0 DAC0_OUT0ALT #0/ OPAMP_OUT0ALT	EBI_A23 #0/1/2	TIM0_CC1 #4 PCNT0_S0IN #2	US0_TX #5 US1_TX #0 I2C0_SDA #4	LES_CH0 #0 PRS_CH2 #0
K2	PC1	ACMP0_CH1 DAC0_OUT0ALT #1/ OPAMP_OUT0ALT	EBI_A24 #0/1/2	TIM0_CC2 #4 PCNT0_S1IN #2	US0_RX #5 US1_RX #0 I2C0_SCL #4	LES_CH1 #0 PRS_CH3 #0
K3	IOVDD_4	Digital IO power supply 4.				
K11	VSS	Ground.				
K12	VSS	Ground.				
K13	PD8	BU_VIN				CMU_CLK1 #1

QFN64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	**Pin Name**	**Analog**	**Timers**	**Communication**	**Other**
50	PF1		TIM0_CC1 #5 LE- TIM0_OUT1 #2	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0/1/2/3 GPIO_EM4WU3
51	PF2		TIM0_CC2 #5	LEU0_TX #4	ACMP1_O #0 DBG_SWO #0 GPIO_EM4WU4
52	USB_VBUS	USB 5.0 V VBUS input.			
53	PF12			USB_ID	
54	PF5		TIM0_CDTI2 #2/5	USB_VBUSEN #0	PRS_CH2 #1
55	IOVDD_5	Digital IO power supply 5.			
56	PE8		PCNT2_S0IN #1		PRS_CH3 #1
57	PE9		PCNT2_S1IN #1		
58	PE10		TIM1_CC0 #1	US0_TX #0	BOOT_TX
59	PE11		TIM1_CC1 #1	US0_RX #0	LES_ALTEX5 #0 BOOT_RX
60	PE12		TIM1_CC2 #1	US0_RX #3 US0_CLK #0 I2C0_SDA #6	CMU_CLK1 #2 LES_ALTEX6 #0
61	PE13			US0_TX #3 US0_CS #0 I2C0_SCL #6	LES_ALTEX7 #0 ACMP0_O #0 GPIO_EM4WU5
62	PE14		TIM3_CC0 #0	LEU0_TX #2	
63	PE15		TIM3_CC1 #0	LEU0_RX #2	
64	PA15		TIM3_CC2 #0		

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
LETIM0_OUT0	PD6	PB11	PF0	PC4				Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5				Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15	PF1	PA0			LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14	PF0	PF2			LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6						LEUART1 Receive input.
LEU1_TX	PC6	PA5						LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8							Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7							Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13			PD6				Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14			PD7				Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3						Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4						Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8						Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9						Pulse Counter PCNT2 input number 1.
PRS_CH0	PA0	PF3						Peripheral Reflex System PRS, channel 0.
PRS_CH1	PA1	PF4						Peripheral Reflex System PRS, channel 1.
PRS_CH2		PF5						Peripheral Reflex System PRS, channel 2.
PRS_CH3		PE8						Peripheral Reflex System PRS, channel 3.
TIM0_CC0	PA0	PA0		PD1	PA0	PF0		Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1		PD2		PF1		Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2		PD3		PF2		Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13		PF3		Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14		PF4		Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	PC4	PF5		Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10		PB7	PD6			Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11		PB8	PD7			Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12		PB11				Timer 1 Capture Compare input / output channel 2.
TIM2_CC0		PA12						Timer 2 Capture Compare input / output channel 0.
TIM2_CC1		PA13						Timer 2 Capture Compare input / output channel 1.
TIM2_CC2		PA14						Timer 2 Capture Compare input / output channel 2.
TIM3_CC0	PE14							Timer 3 Capture Compare input / output channel 0.

5.15 EFM32LG890 (BGA112)

5.15.1 Pinout

The EFM32LG890 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

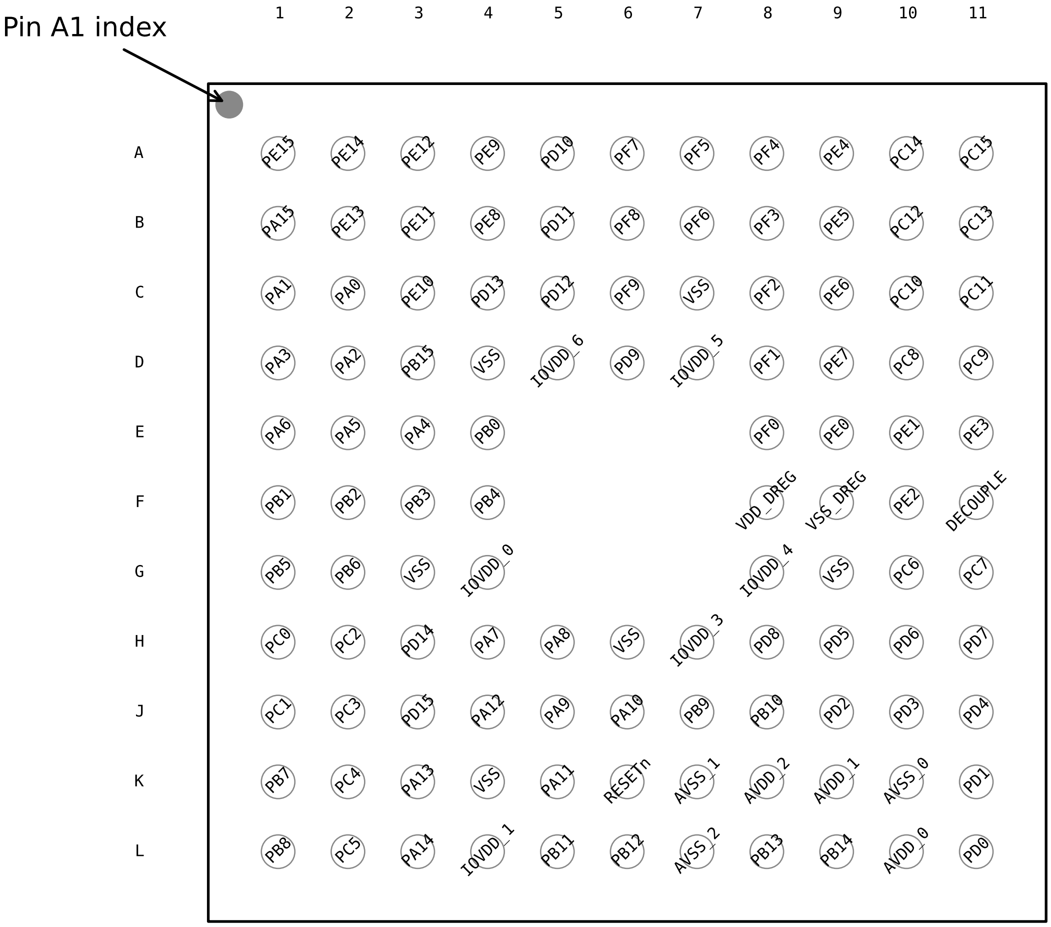

Figure 5.29. EFM32LG890 Pinout (top view, not to scale)

Table 5.43. Device Pinout

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
A1	PE15	LCD_SEG11	EBI_AD07 #0/1/2	TIM3_CC1 #0	LEU0_RX #2	
A2	PE14	LCD_SEG10	EBI_AD06 #0/1/2	TIM3_CC0 #0	LEU0_TX #2	

BGA120 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	**Pin Name**	**Analog**	**EBI**	**Timers**	**Communication**	**Other**
K13	PD8	BU_VIN				CMU_CLK1 #1
L1	PC2	ACMP0_CH2 DAC0_OUT0ALT #2/ OPAMP_OUT0ALT	EBI_A25 #0/1/2	TIM0_CDTI0 #4	US2_TX #0	LES_CH2 #0
L2	PC3	ACMP0_CH3 DAC0_OUT0ALT #3/ OPAMP_OUT0ALT	EBI_NANDREn #0/1/2	TIM0_CDTI1 #4	US2_RX #0	LES_CH3 #0
L3	PA7	LCD_SEG35	EBI_CSTFT #0/1/2			
L4	IOVDD_5	Digital IO power supply 5.				
L5	VSS	Ground.				
L6	VSS	Ground.				
L7	IOVDD_6	Digital IO power supply 6.				
L8	PB9		EBI_A03 #0/1/2		U1_TX #2	
L9	PB10		EBI_A04 #0/1/2		U1_RX #2	
L10	PD0	ADC0_CH0 DAC0_OUT0ALT #4/ OPAMP_OUT0ALT OPAMP_OUT2 #1		PCNT2_S0IN #0	US1_TX #1	
L11	PD1	ADC0_CH1 DAC0_OUT1ALT #4/ OPAMP_OUT1ALT		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	DBG_SWO #2
L12	PD4	ADC0_CH4 OPAMP_P2			LEU0_TX #0	ETM_TD2 #0/2
L13	PD7	ADC0_CH7 OPAMP_N1		TIM1_CC1 #4 LE-TIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 #0 ACMP1_O #2 ETM_TCLK #0
M1	PB7	LFXTAL_P		TIM1_CC0 #3	US0_TX #4 US1_CLK #0	
M2	PC4	ACMP0_CH4 OPAMP_P0	EBI_A26 #0/1/2	TIM0_CDTI2 #4 LE-TIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0 I2C1_SDA #0	LES_CH4 #0
M3	PA8	LCD_SEG36	EBI_DCLK #0/1/2	TIM2_CC0 #0		
M4	PA10	LCD_SEG38	EBI_VSNC #0/1/2	TIM2_CC2 #0		
M5	PA13	LCD_BCAP_N	EBI_A01 #0/1/2	TIM2_CC1 #1		
M6	PA14	LCD_BEXT	EBI_A02 #0/1/2	TIM2_CC2 #1		
M7	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
M8	AVSS_1	Analog ground 1.				
M9	AVDD_2	Analog power supply 2.				

5.16.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.47. Alternate functionality overview

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ACMP0_CH0	PC0							Analog comparator ACMP0, channel 0.
ACMP0_CH1	PC1							Analog comparator ACMP0, channel 1.
ACMP0_CH2	PC2							Analog comparator ACMP0, channel 2.
ACMP0_CH3	PC3							Analog comparator ACMP0, channel 3.
ACMP0_CH4	PC4							Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5							Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6							Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7							Analog comparator ACMP0, channel 7.
ACMP0_O	PE13	PE2	PD6					Analog comparator ACMP0, digital output.
ACMP1_CH0	PC8							Analog comparator ACMP1, channel 0.
ACMP1_CH1	PC9							Analog comparator ACMP1, channel 1.
ACMP1_CH2	PC10							Analog comparator ACMP1, channel 2.
ACMP1_CH3	PC11							Analog comparator ACMP1, channel 3.
ACMP1_CH4	PC12							Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13							Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14							Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15							Analog comparator ACMP1, channel 7.
ACMP1_O	PF2	PE3	PD7					Analog comparator ACMP1, digital output.
ADC0_CH0	PD0							Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1							Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2							Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3							Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4							Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5							Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6							Analog to digital converter ADC0, input channel number 6.

5.17 EFM32LG900 (Wafer)

5.17.1 Padout

The EFM32LG900 padout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pad are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the *_ROUTE register in the module in question.

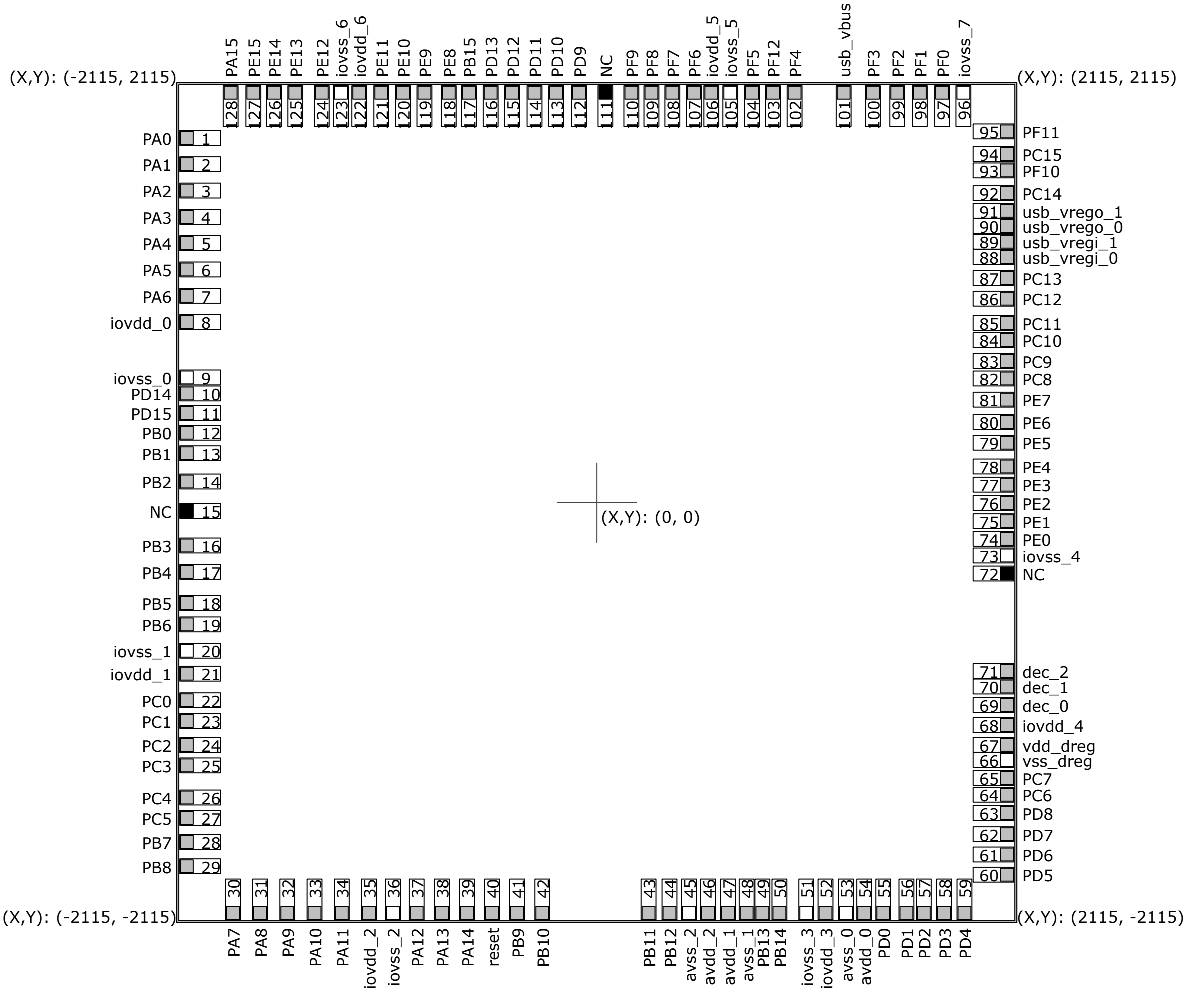

Figure 5.33. EFM32LG900 Padout (top view, not to scale)

The pad coordinates represent the center of the pad opening relative to the die center.

Table 5.49. Device Padout

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (µm)	Y (µm)	Analog	EBI	Timers	Communica-tion	Other
1	PA0	-2065.0	1837.0	LCD_SEG13	EBI_AD09 #0/1/2	TIM0_CC0 #0/1/4	LEU0_RX #4 I2C0_SDA #0	PRS_CH0 #0 GPIO_EM4WU0
2	PA1	-2065.0	1704.6	LCD_SEG14	EBI_AD10 #0/1/2	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0 PRS_CH1 #0
3	PA2	-2065.0	1572.1	LCD_SEG15	EBI_AD11 #0/1/2	TIM0_CC2 #0/1		CMU_CLK0 #0 ETM_TD0 #3

Water Pads and Coordinates				Pad Alternative Functionality / Description				
Pad #	Pad Name	X (µm)	Y (µm)	Analog	EBI	Timers	Communication	Other
92	PC14	2065.0	1558.7	ACMP1_CH6 DAC0_OUT1ALT #2/ OPAMP_OUT1ALT		TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0	US0_CS #3 U0_TX #3	LES_CH14 #0
93	PF10	2065.0	1673.6				U1_TX #1 USB_DM	
94	PC15	2065.0	1756.6	ACMP1_CH7 DAC0_OUT1ALT #3/ OPAMP_OUT1ALT		TIM0_CDTI2 #1/3 TIM1_CC2 #0	US0_CLK #3 U0_RX #3	LES_CH15 #0 DBG_SWO #1
95	PF11	2065.0	1870.0				U1_RX #1 USB_DP	
96	IOVSS_7	1846.0	2065.0	Digital IO ground 7.				
97	PF0	1739.3	2065.0			TIM0_CC0 #5 LETIM0_OUT0 #2	US1_CLK #2 LEU0_TX #3 I2C0_SDA #5	DBG_SWCLK #0/1/2/3
98	PF1	1626.3	2065.0			TIM0_CC1 #5 LETIM0_OUT1 #2	US1_CS #2 LEU0_RX #3 I2C0_SCL #5	DBG_SWDIO #0/1/2/3 GPIO_EM4WU3
99	PF2	1513.2	2065.0	LCD_SEG0	EBI_ARDY #0/1/2	TIM0_CC2 #5	LEU0_TX #4	ACMP1_O #0 DBG_SWO #0 GPIO_EM4WU4
100	PF3	1389.7	2065.0	LCD_SEG1	EBI_ALE #0	TIM0_CDTI0 #2/5		PRS_CH0 #1 ETM_TD3 #1
101	USB_VBUS	1242.9	2065.0	USB 5.0 V VBUS input.				
102	PF4	995.9	2065.0	LCD_SEG2	EBI_WEn #0/2	TIM0_CDTI1 #2/5		PRS_CH1 #1
103	PF12	886.3	2065.0				USB_ID	
104	PF5	782.2	2065.0	LCD_SEG3	EBI_REn #0/2	TIM0_CDTI2 #2/5	USB_VBUSEN #0	PRS_CH2 #1
105	IOVSS_5	672.3	2065.0	Digital IO ground 5.				
106	IOVDD_5	576.7	2065.0	Digital IO power supply 5.				
107	PF6	488.4	2065.0	LCD_SEG24	EBI_BL0 #0/1/2	TIM0_CC0 #2	U0_TX #0	
108	PF7	380.5	2065.0	LCD_SEG25	EBI_BL1 #0/1/2	TIM0_CC1 #2	U0_RX #0	
109	PF8	275.3	2065.0	LCD_SEG26	EBI_WEn #1	TIM0_CC2 #2		ETM_TCLK #1
110	PF9	174.3	2065.0	LCD_SEG27	EBI_REn #1			ETM_TD0 #1
111	NC	43.2	2065.0	Do not connect.				
112	PD9	-89.5	2065.0	LCD_SEG28	EBI_CS0 #0/1/2			
113	PD10	-204.5	2065.0	LCD_SEG29	EBI_CS1 #0/1/2			

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
ETM_TD2	PD4	PB15	PD4	PA4				Embedded Trace Module ETM data 2.
ETM_TD3	PD5	PF3	PD5	PA5				Embedded Trace Module ETM data 3.
GPIO_EM4WU0	PA0							Pin can be used to wake the system up from EM4
GPIO_EM4WU1	PA6							Pin can be used to wake the system up from EM4
GPIO_EM4WU2	PC9							Pin can be used to wake the system up from EM4
GPIO_EM4WU3	PF1							Pin can be used to wake the system up from EM4
GPIO_EM4WU4	PF2							Pin can be used to wake the system up from EM4
GPIO_EM4WU5	PE13							Pin can be used to wake the system up from EM4
HFXTAL_N	PB14							High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13							High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7	PD15	PC1	PF1	PE13	I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6	PD14	PC0	PF0	PE12	I2C0 Serial Data input / output.
I2C1_SCL	PC5	PB12	PE1					I2C1 Serial Clock Line input / output.
I2C1_SDA	PC4	PB11	PE0					I2C1 Serial Data input / output.
LCD_BCAP_N	PA13							LCD voltage booster (optional), boost capacitor, negative pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BCAP_P	PA12							LCD voltage booster (optional), boost capacitor, positive pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BEXT	PA14							LCD voltage booster (optional), boost output. If using the LCD voltage booster, connect a 1 uF capacitor between this pin and VSS. An external LCD voltage may also be applied to this pin if the booster is not enabled. If AVDD is used directly as the LCD supply voltage, this pin may be left unconnected or used as a GPIO.
LCD_COM0	PE4							LCD driver common line number 0.
LCD_COM1	PE5							LCD driver common line number 1.
LCD_COM2	PE6							LCD driver common line number 2.
LCD_COM3	PE7							LCD driver common line number 3.
LCD_SEG0	PF2							LCD segment line 0. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG1	PF3							LCD segment line 1. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG2	PF4							LCD segment line 2. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG3	PF5							LCD segment line 3. Segments 0, 1, 2 and 3 are controlled by SEGEN0.

Alternate	LOCATION							
Functionality	0	1	2	3	4	5	6	Description
EBI_AD10	PA1	PA1	PA1					External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2	PA2	PA2					External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3	PA3	PA3					External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4	PA4	PA4					External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5	PA5	PA5					External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6	PA6	PA6					External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE		PC11	PC11					External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	PF2	PF2	PF2					External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	PF6	PF6	PF6					External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	PF7	PF7	PF7					External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	PD9	PD9	PD9					External Bus Interface (EBI) Chip Select output 0.
EBI_CS1	PD10	PD10	PD10					External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	PD11	PD11	PD11					External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	PD12	PD12	PD12					External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	PA7	PA7	PA7					External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	PA8	PA8	PA8					External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	PA9	PA9	PA9					External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNC	PA11	PA11	PA11					External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREn	PC3	PC3	PC3					External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEn	PC5	PC5	PC5					External Bus Interface (EBI) NAND Write Enable output.
EBI_REn	PF5	PF9	PF5					External Bus Interface (EBI) Read Enable output.
EBI_VSNC	PA10	PA10	PA10					External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEn		PF8						External Bus Interface (EBI) Write Enable output.
ETM_TCLK	PD7	PF8	PC6	PA6				Embedded Trace Module ETM clock .
ETM_TD0	PD6	PF9	PC7	PA2				Embedded Trace Module ETM data 0.
ETM_TD1	PD3		PD3	PA3				Embedded Trace Module ETM data 1.
ETM_TD2	PD4		PD4	PA4				Embedded Trace Module ETM data 2.

Symbol	Dim. (mm)
c	0.50
d	15.40
e	15.40

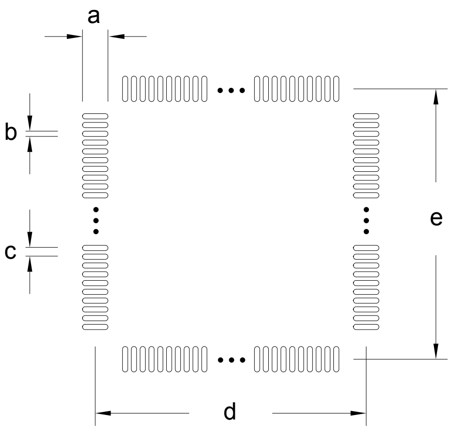

Figure 9.4. LQFP100 PCB Stencil Design

Table 9.4. LQFP100 PCB Stencil Design Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.35
b	0.20
c	0.50
d	15.40
e	15.40

Note:

1. The drawings are not to scale.
2. All dimensions are in millimeters.
3. All drawings are subject to change without notice.
4. The PCB Land Pattern drawing is in compliance with IPC-7351B.
5. Stencil thickness 0.125 mm.
6. For detailed pin-positioning, see Pin Definitions.

12. Wafer Specifications

12.1 Bonding Instructions

All pads should be bonded out, with the exception of the pads labeled “NC” and listed as “Do not connect” in Padout. Gold bond wires are recommended for these devices.

All three voltage regulator output decouple pads (DEC_0, DEC_1, DEC_2) must be bonded out andelectrically connected on the PCB. In the packaged devices, these three pads are all bonded to a single DECOUPLE pin.

If the USB feature of EFM32LG900 will be used, all of the USB pads must be bonded out, and

- both USB_VREGO_0 and USB_VREGO_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGO pin.
- both USB_VREGI_0 and USB_VREGI_1 must be bonded out and electrically connected on the PCB. In the packaged devices, these two pads are both bonded to a single USB_VREGI pin.

12.2 Wafer Description

Table 12.1. Wafer and Die Information

Parameter	Value
Device Family	EFM32LG (Leopard Gecko)
Wafer Diameter	8 in
Die Dimensions (Outer edge of seal ring)	4230 µm × 4230 µm
Wafer Thickness (No backgrind)	725 µm ±15 µm (28.54 mil ±1 mil)
Wafer Identification	Notch
Scribe Street Width	80 µm × 160 µm
Die Per Wafer[1]	Contact sales for information
Passivation	Standard
Wafer Packaging Detail	Wafer Jar
Bond Pad Dimensions	65 µm (parallel to die edge) × 66 µm
Bond Pad Pitch Minimum	76 µm
Maximum Processing Temperature	250°C
Electronic Die Map Format	.txt

Note:

1. This is the Expected Known Good Die yielded per wafer and represents the batch order quantity (one wafer).

12.2.1 Environmental

Bare silicon die are susceptible to mechanical damage and may be sensitive to light. When bare die must be used in an environment exposed to light, it may be necessary to cover the top and sides with an opaque material.

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.